Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	600	V
Drain Current	I_D	7	A
Drain Current - Pulsed	I_{DM}	28	A
Gate-Source Voltage	V_{GSS}	±30	V
Single Pulsed Avalanche Energy	E_{AS}	500	mJ
Repetitive Avalanche Energy	E_{AR}	54	mJ
Single Pulse Avalanche Current	I_{AS}	3.3	A
Power Dissipation	P_D(Tc=25		

/ Electrical Characteristic Curve

Figure1. Output Characteristics (Tj=25℃)

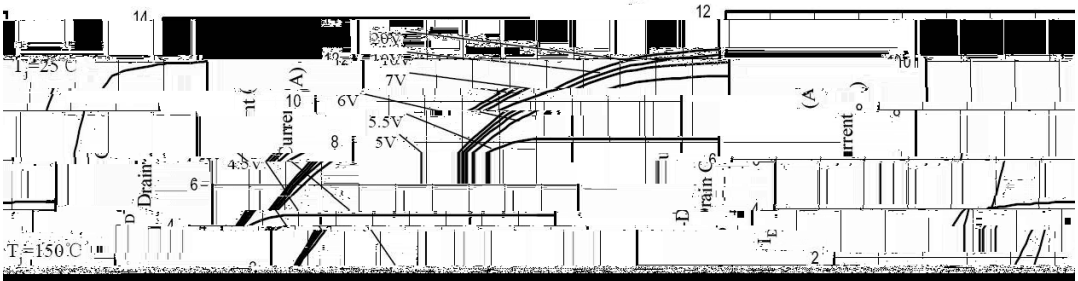


Figure5. Transfer Characteristics

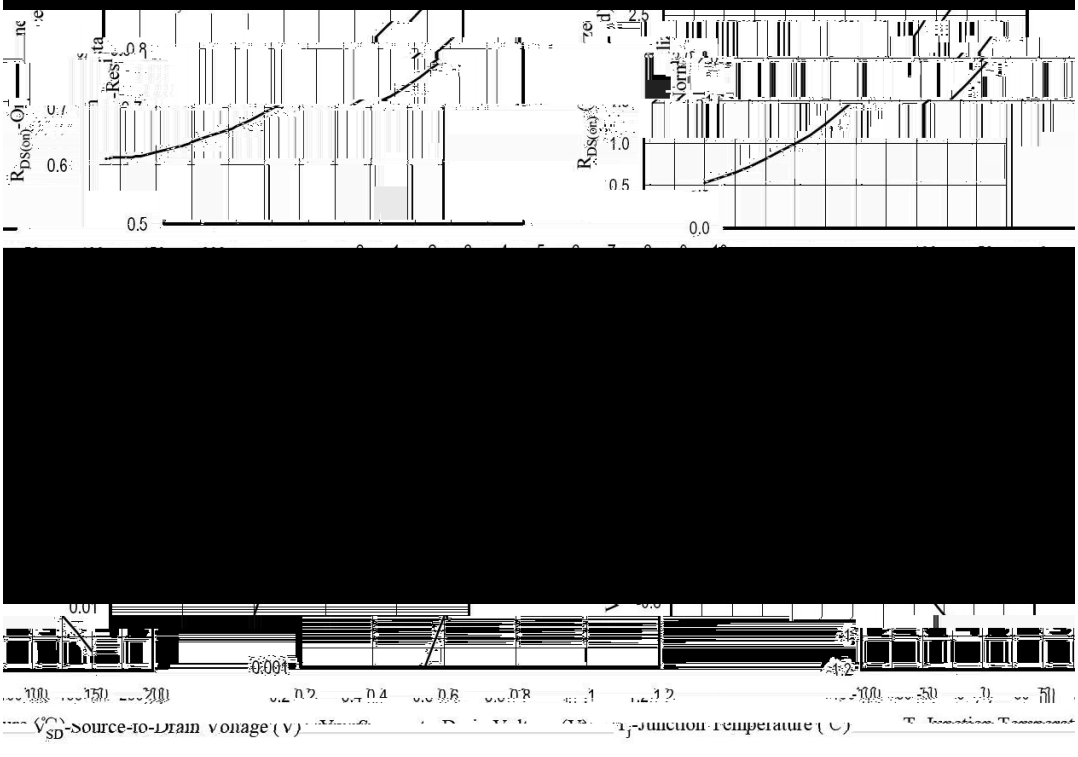
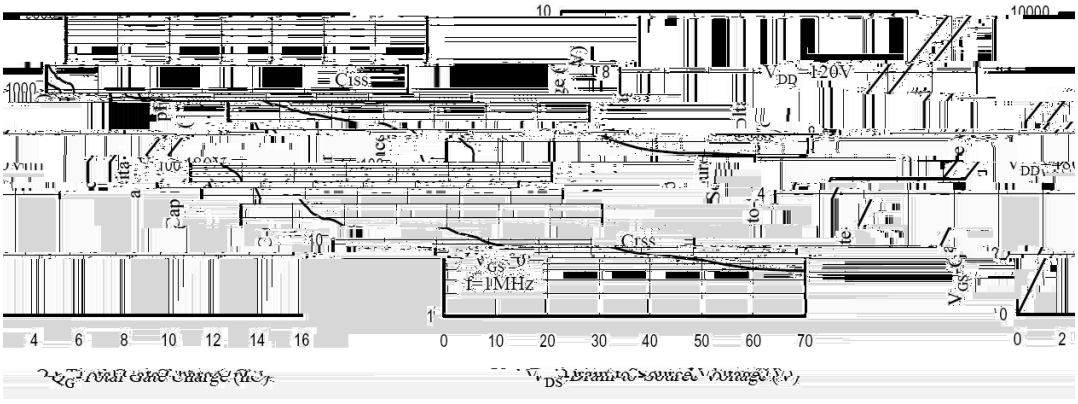
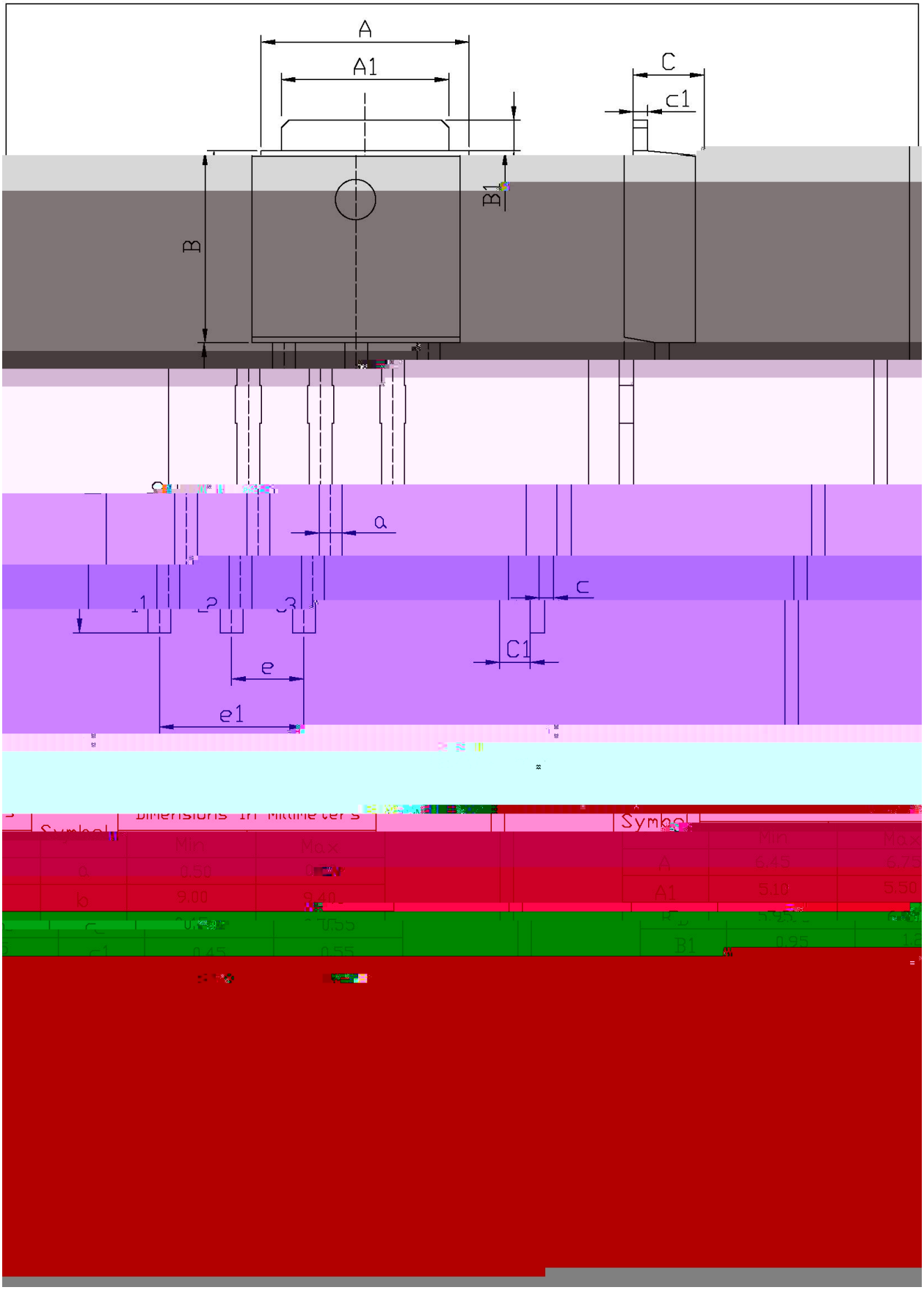


Figure7. Capacitance

Figure8. Gate Charge



/ Package Dimensions



( ) / Temperature Profile for Dip Soldering(Pb-Free)

				Note:
1	25	150	60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2	255±5		5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3		2 10 /sec.		3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±